

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IAUC60N04S6N031H	**Issued**	08. April 2022
MA#	MA002039116		
Package	PG-TDSON-8-56	**Weight***	100.09 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	0.475	0.47	0.47	4741	4741
chip_2	inorganic material	silicon	7440-21-3	0.475	0.47	0.47	4741	4741
leadframe	inorganic material	phosphorus	7723-14-0	0.014	0.01		136	
	non noble metal	iron	7439-89-6	0.045	0.05		452	
	non noble metal	copper	7440-50-8	45.219	45.19	45.25	451800	452388
wire	noble metal	gold	7440-57-5	0.060	0.06	0.06	604	604
encapsulation	organic material	carbon black	1333-86-4	0.080	0.08		803	
	plastics	epoxy resin	-	6.352	6.35		63467	
	inorganic material	silicondioxide	60676-86-0	33.770	33.74	40.17	337417	401687
leadfinish	non noble metal	tin	7440-31-5	0.512	0.51	0.51	5118	5118
plating	noble metal	silver	7440-22-4	0.240	0.24	0.24	2396	2396
solder	non noble metal	tin	7440-31-5	0.028	0.03		281	
	noble metal	silver	7440-22-4	0.035	0.04		351	
	non noble metal	lead	7439-92-1	1.342	1.34	1.41	13411	14043
heat sink clip	inorganic material	phosphorus	7723-14-0	0.003			33	
	non noble metal	iron	7439-89-6	0.011	0.01		111	
	non noble metal	copper	7440-50-8	11.140	11.13	11.14	111307	111451
heatspreader	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	iron	7439-89-6	0.000			3	
	non noble metal	copper	7440-50-8	0.283	0.28	0.28	2827	2831
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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